

This listing of claims will replace all prior versions, and listings, of claims in the application.

In the Claims:

1. (CURRENTLY AMENDED) Method for the production of a swage in a workpiece in which material is removed in a layer-wise manner by means of a laser beam, comprising:

removing material of the workpiece in a layer-wise manner by a laser beam,

characterised in that

the side walls of the swage are treated by means of a laser beam and/or a processing means after several layers have been removed.

2. (ORIGINAL) Method according to claim 1, characterised in that the side walls are treated over all or part of the depth of the swage and/or all or a part of the circumference of the swage.

3. CANCELED.

4. (PREVIOUSLY PRESENTED) Method according to claim 1, characterised in that the treatment of the side wall is performed with a reduced power of the laser beam and/or defocused at the treated position and/or with a higher beam guidance speed and/or with a reduced energy input per surface unit.

5. (PREVIOUSLY PRESENTED) Method according to claim 1, characterised in that the treatment of the side wall is performed automatically in accordance with swage data.

6. (PREVIOUSLY PRESENTED) Method according to claim 1, characterised in that the treatment of the side wall is performed with a relative positioning of the workpiece and the laser source which is different from the relative positioning during the material removal in layers.

7. (PREVIOUSLY PRESENTED) Method according to claim 1, characterised in that the side wall is measured before the treatment and that the treatment is performed in accordance with the measurement.

8. CANCELED.

9. (CURRENTLY AMENDED) Method according to claim 1, characterised in that the processing means ~~[[is]]~~ comprises at least one of a particle blast ~~[[and/or]]~~, an etching reagent ~~[[and/or contains]]~~, dry ice, and/or ultrasonic waves.

10. (ORIGINAL) Method according to claim 9, characterised in that the processing means is supplied to the vicinity of the swage by means of a conduit.

11. (ORIGINAL) Method according to claim 10, characterised in that the position and/or angular position of the conduit relative to the workpiece is adjustable and/or guidable during the treatment of the side wall.

12. (ORIGINAL) Method according to claim 11, characterised in that the position and/or angular position of the conduit relative to the workpiece is adjusted and/or guided in accordance with swage data and/or in accordance with measured depth data.

13. (CURRENTLY AMENDED) Method according to claim 9, characterised in that at ~~least the machine is shielded from~~ excessive processing means is shielded during the treatment of the side walls.

14. (PREVIOUSLY PRESENTED) Method according to claim 13, characterised in that the excessive processing means is removed, particularly removed by suction, during the treatment of the side walls.

15. (PREVIOUSLY PRESENTED) Method according to claim 10, characterised in that the workpiece is automatically removed from the work area of the laser beam and moved to the vicinity of the conduit of the processing means for the treatment of the side walls.

16. (PREVIOUSLY PRESENTED) Method according to claim 10, characterised in that the conduit of the processing means is moved into the work area of the laser beam for the treatment of the side walls.

17. CANCELED.

18. (CURRENTLY AMENDED) Device for the production of a swage, particularly for performing the method according to claim 1, comprising:

a laser treatment means ~~[[and]]~~;

a processing means;

a feeding means for the processing means; and

a control means for the laser treatment means, characterised in that

wherein the control means is adapted configured to drive the laser treatment means or ~~[[a]]~~ the feeding means for the processing means for treating the side wall of the swage such that a plurality of layers of material is removed and then the side wall is treated.

19. (PREVIOUSLY PRESENTED) Device according to claim 18, characterised by a focusing means defocusing the laser treatment means at the work area during the treatment of the side wall.

20. (PREVIOUSLY PRESENTED) Device according to claim 18 or 19, characterised by a power control means reducing laser power during the treatment of the side wall.

21. (WITHDRAWN) Device according to claim 18, characterised in that the processing means is a particle blast and/or an etching reagent and/or contains dry ice.

22. (WITHDRAWN) Device according to claim 18, characterised in that the feeding means comprises a conduit for the particles of the particle blast and/or the etching reagent and/or the dry ice.

23. (WITHDRAWN) Device according to claim 18, characterised by a shielding means shielding at least the device from the processing means.

24. (WITHDRAWN) Device according to claim 18, characterised by a suction means for removing excessive processing means by suction.

25. (WITHDRAWN) Device according to claim 18, characterised in that the control means is adapted to drive an ultrasound means for treating the side wall of the swage.